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## 5 ABSTRACT

An encapsulated circuit comprising a thin interface layer with one or more vias for input/output interface to the circuit. The encapsulated circuit further comprises one or more sequentially processed circuit layers added to one side 10 of the interface circuit. The sequentially processed circuit layers are preferably made by additive offset printing technology. The encapsulated circuit further comprises a layer of adhesive. A first side of the adhesive layer is attached on top of the uppermost and most exposed circuit layer. The encapsulated circuit further comprises a support carrier attached on a second side of the adhesive 15 layer.

(Fig. 1)